



## UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
 United States Patent and Trademark Office  
 Address: COMMISSIONER FOR PATENTS  
 P.O. Box 1450  
 Alexandria, Virginia 22313-1450  
 www.uspto.gov



Bib Data Sheet

CONFIRMATION NO. 2568

<b>SERIAL NUMBER</b> 09/690,600	<b>FILING OR 371(c) DATE</b> 10/17/2000 <b>RULE</b>	<b>CLASS</b> 257	<b>GROUP ART UNIT</b> 2891	<b>ATTORNEY DOCKET NO.</b> 53434USA8C.009
------------------------------------	---	---------------------	-------------------------------	--

**APPLICANTS**

Peter B. Hogerton, White Bear Lake, MN;  
 Kevin Yu Chen, San Diego, CA;  
 Joel A. Gerber, Orono, MN;  
 Robert L. D. Zenner, Minneapolis, MN;

**\*\* CONTINUING DATA \*\*\*\*\***

This application is a CIP of 08/986,661 12/08/1997 PAT 6,260,264 *LT*

**\*\* FOREIGN APPLICATIONS \*\*\*\*\***

(None) *LT*

**F REQUIRED, FOREIGN FILING LICENSE GRANTED \*\***  
 11/24/2000

Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	<b>STATE OR COUNTRY</b> MN	<b>SHEETS DRAWING</b> 17	<b>TOTAL CLAIMS</b> 4 <i>25</i>	<b>INDEPENDENT CLAIMS</b> 1 <i>4</i>
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged <i>Shallman</i> Examiner's Signature	<i>LT</i> Initials			

**ADDRESS**

32692

**TITLE**

Solvent assisted burnishing of pre-underfilled solder bumped wafers for flipchip bonding

<b>FILING FEE RECEIVED</b> 974	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
		<input type="checkbox"/> 1.16 Fees ( Filing )
		<input type="checkbox"/> 1.17 Fees ( Processing Ext. of time )
		<input type="checkbox"/> 1.18 Fees ( Issue )
		<input type="checkbox"/> Other _____
		<input type="checkbox"/> Credit